SUSS MICROTEC INVESTOR PRESENTATION

September 2014

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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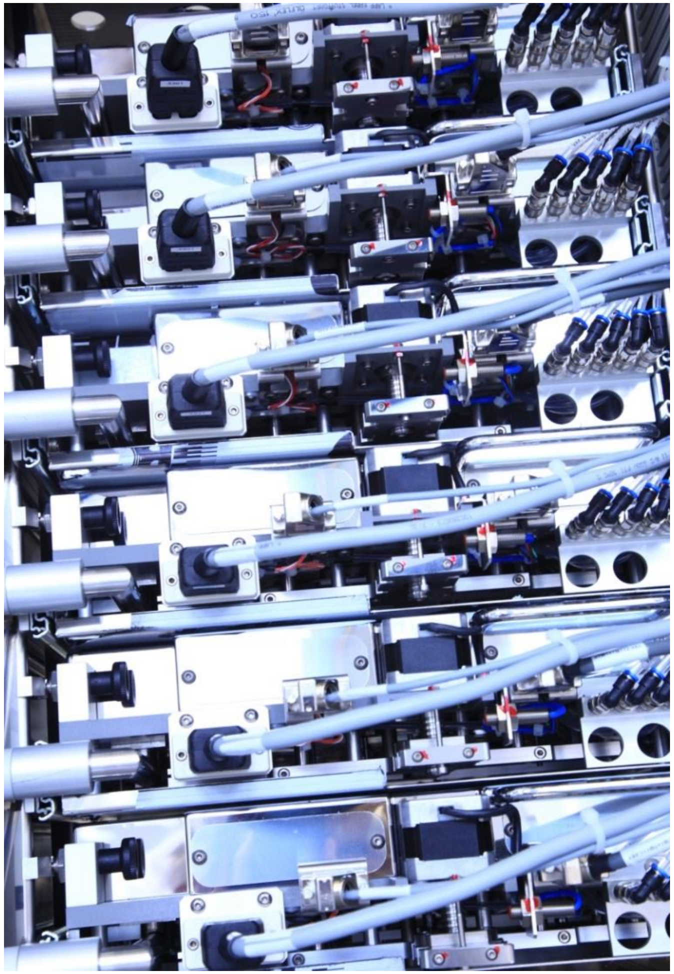
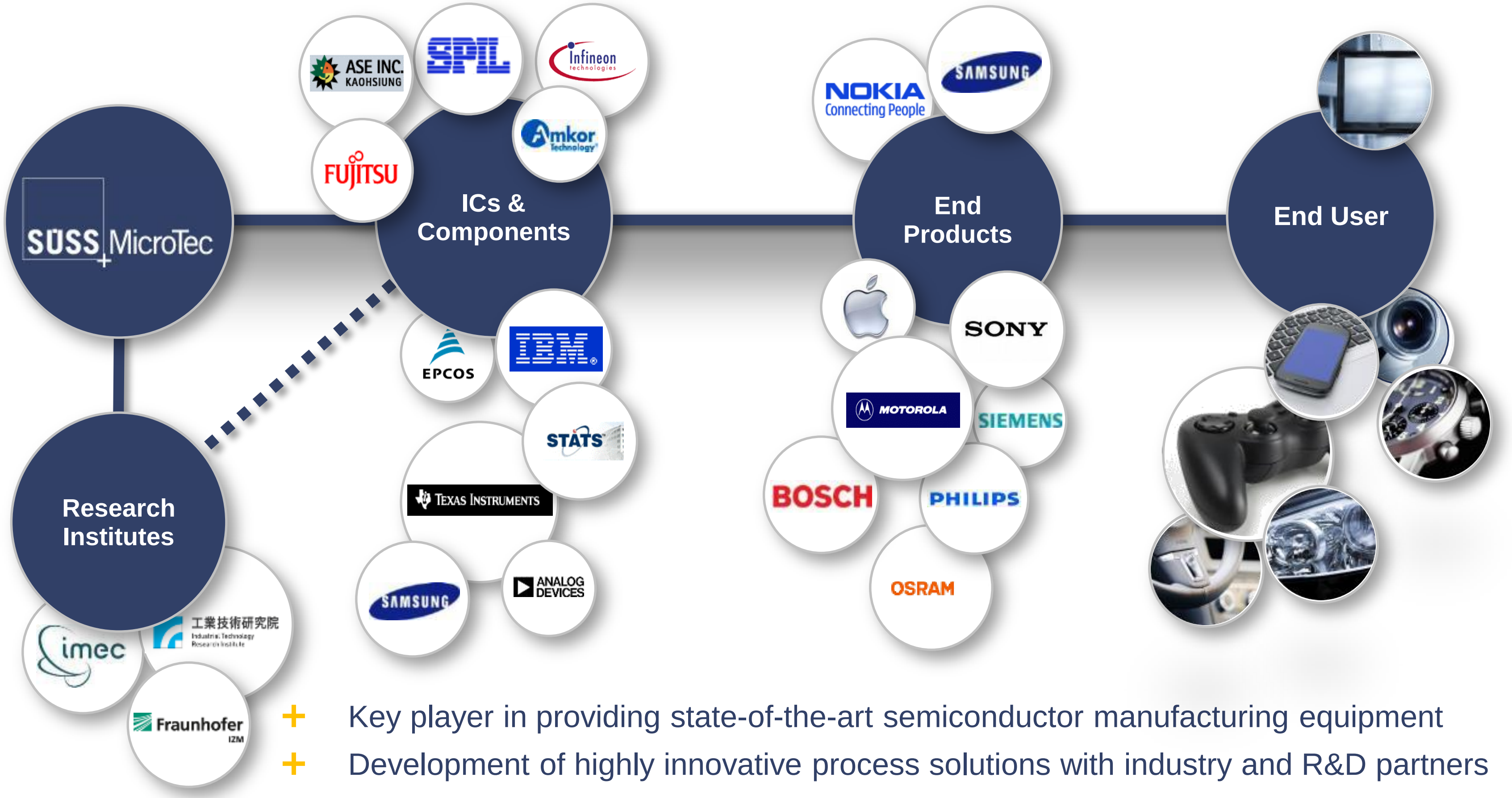
SUSS MICROTEC AT A GLANCE

- A global leader in manufacturing equipment for the semiconductor mid- and backend market
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- Focused on attractive growth markets: Semiconductors, MEMS and LED
- Leading market position in target markets
- SUSS MicroTec is listed in the Prime Standard of Deutsche Boerse



SUSS MICROTEC IN THE VALUE CHAIN



SUSS MicroTec

ICs & Components

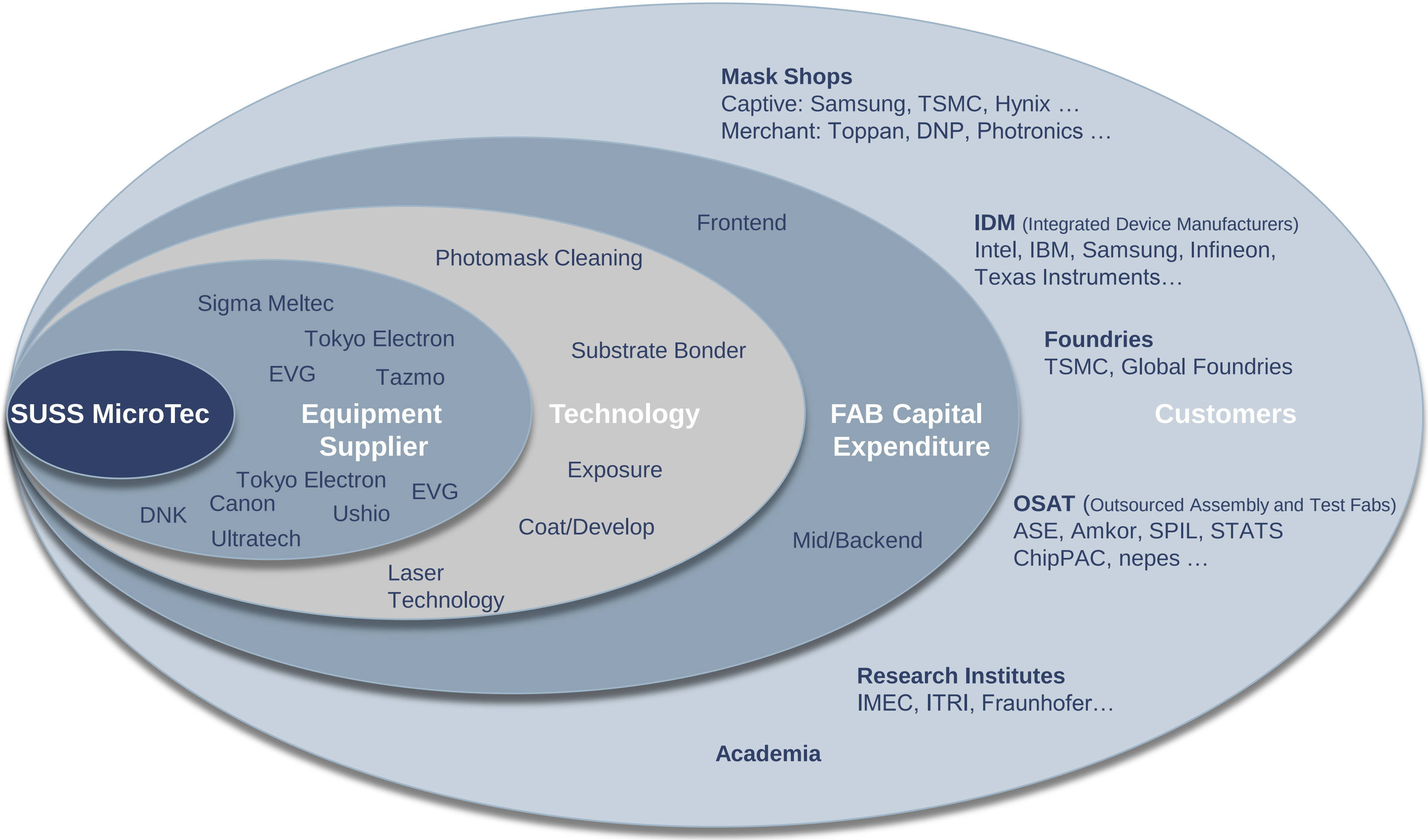
End Products

End User

Research Institutes

- Key player in providing state-of-the-art semiconductor manufacturing equipment
- Development of highly innovative process solutions with industry and R&D partners
- Key components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec’s equipment

THE SEMICONDUCTOR MARKET



Mask Shops
Captive: Samsung, TSMC, Hynix …
Merchant: Toppan, DNP, Photronics …

IDM (Integrated Device Manufacturers)
Intel, IBM, Samsung, Infineon, Texas Instruments…

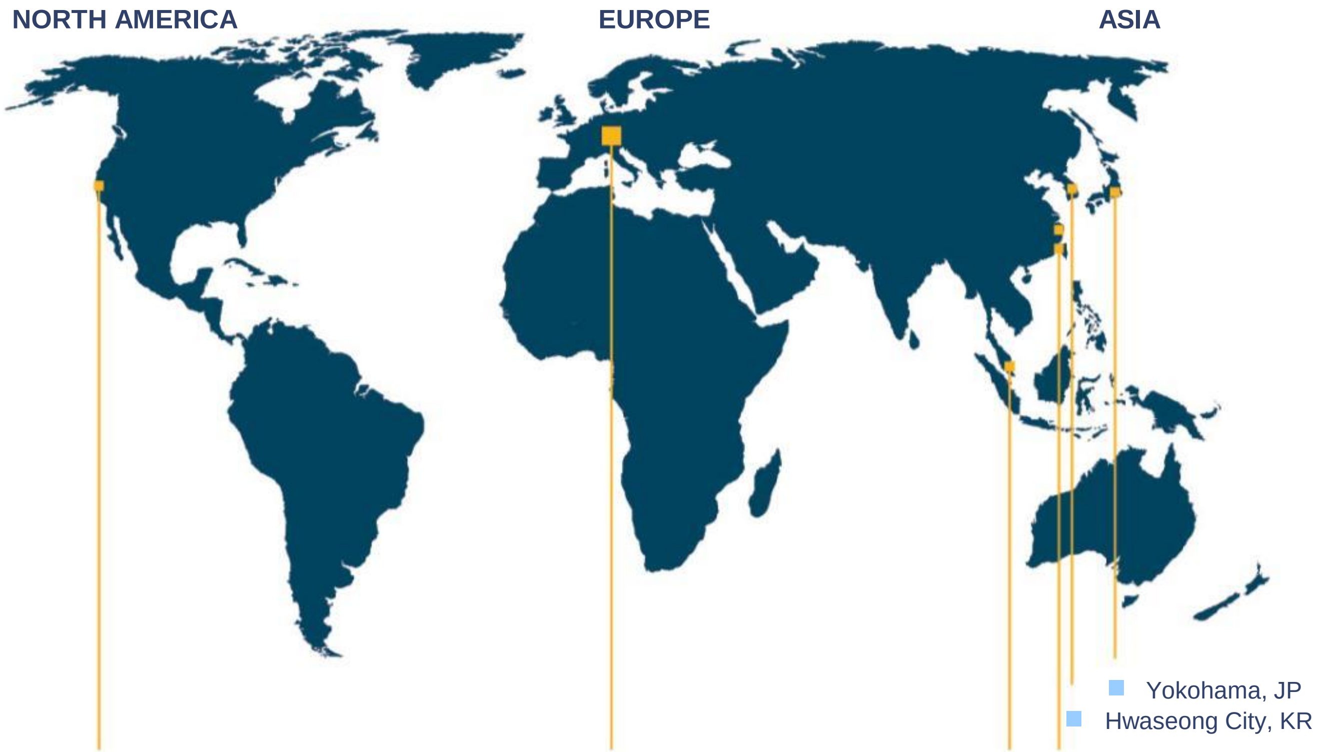
Foundries
TSMC, Global Foundries

OSAT (Outsourced Assembly and Test Fabs)
ASE, Amkor, SPIL, STATS ChipPAC, nepes …

Research Institutes
IMEC, ITRI, Fraunhofer…

Academia

SUSS MICROTEC – A GLOBAL PLAYER



- 🟦 Sunnyvale, US
- ▨ Corona, US

- ■ ▨ Garching, DE
- ▨ Sternenfels, DE
- ▨ Hâuterive, CH
- 🟦 Pierre-Bénite, FR
- 🟦 Coventry, UK

- Singapore, SG 🟦

- 🟦 Yokohama, JP
- 🟦 Hwaseong City, KR
- 🟦 Shanghai, CN
- 🟦 Hsinchu, TW

- ■ Headquarters
- ▨ Production
- 🟦 Sales

MAIN PRODUCTION SITES

Germany

Garching*

- SUSS MicroTec HQ
- Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
- Core competencies:
  - **Exposure** (proximity exposure)
  - **Alignment**

Sternenfels*

- Development/production :
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
- Core competencies:
  - **Wet processing**
  - **Wafer bonding**

USA

Corona

- Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
- Core competencies:
  - **Exposure** (UV projection)
  - **Laser Ablation**

*Production site is owned by SUSS MicroTec

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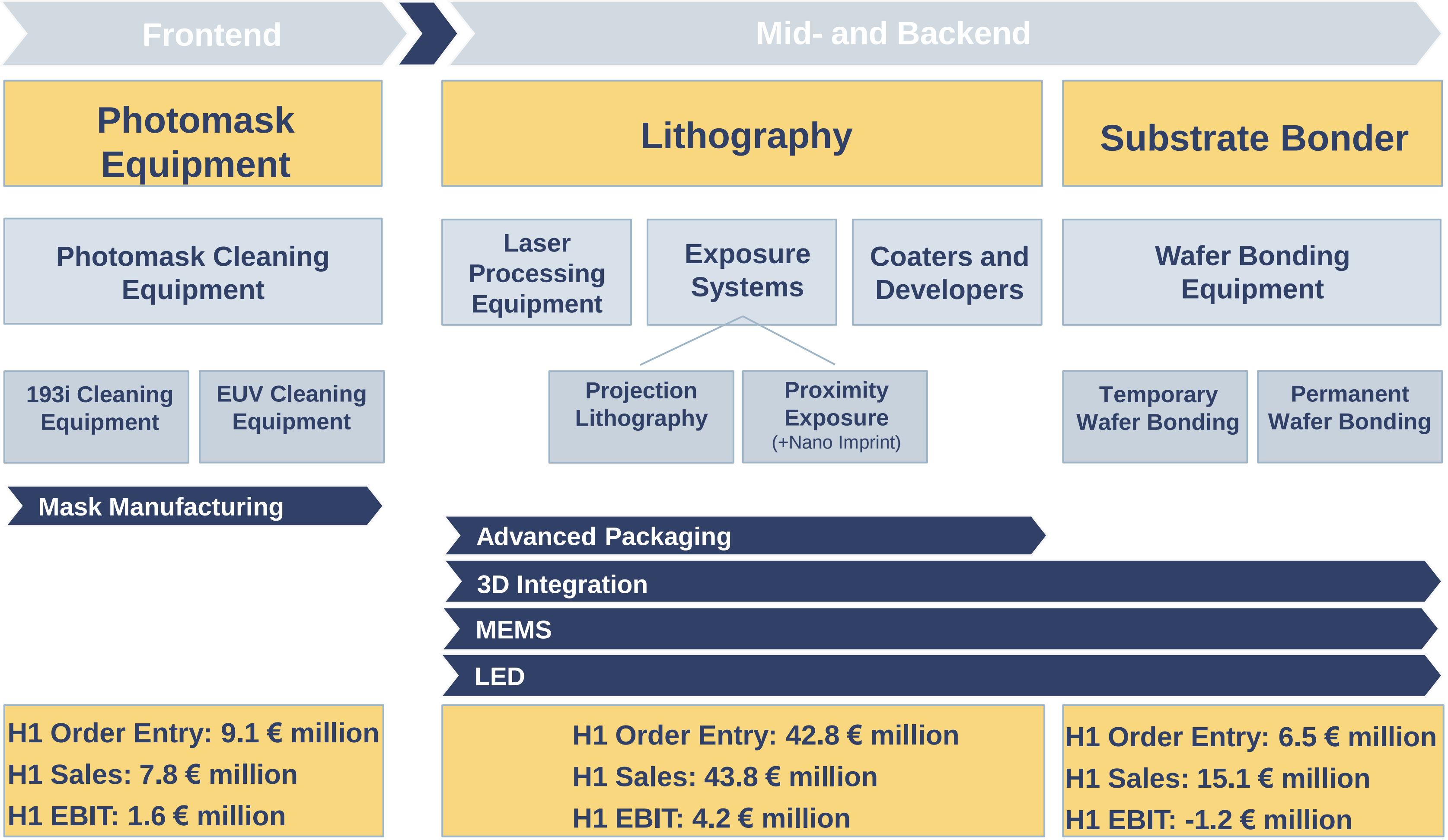
SEGMENTS, PRODUCTS AND MARKETS



Frontend

Mid- and Backend

Photomask Equipment

- Photomask Cleaning Equipment
  - 193i Cleaning Equipment
  - EUV Cleaning Equipment

Mask Manufacturing

H1 Order Entry: 9.1 € million
H1 Sales: 7.8 € million
H1 EBIT: 1.6 € million

Lithography

- Laser Processing Equipment
- Exposure Systems
  - Projection Lithography
  - Proximity Exposure (+Nano Imprint)
- Coaters and Developers

H1 Order Entry: 42.8 € million
H1 Sales: 43.8 € million
H1 EBIT: 4.2 € million

Substrate Bonder

- Wafer Bonding Equipment
  - Temporary Wafer Bonding
  - Permanent Wafer Bonding

H1 Order Entry: 6.5 € million
H1 Sales: 15.1 € million
H1 EBIT: -1.2 € million

Advanced Packaging

3D Integration

MEMS

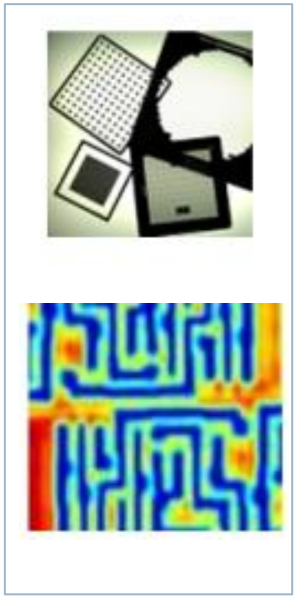
LED

KEY MARKETS - OVERVIEW

Semiconductors

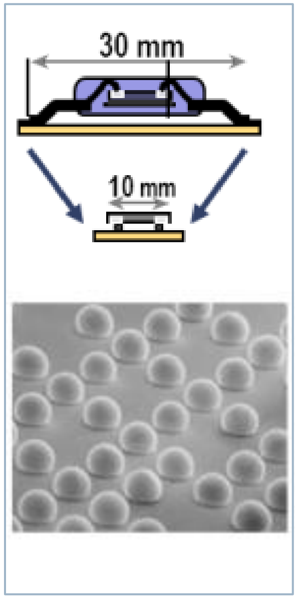
Mask Making

Photomask Cleaning



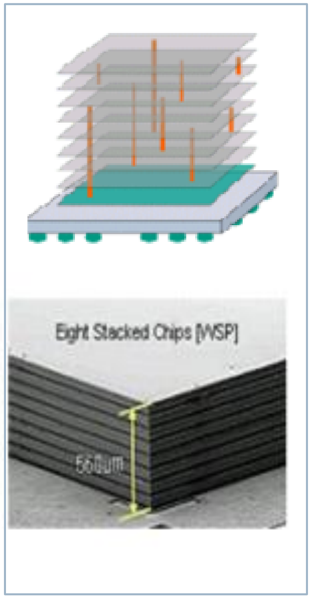
Advanced Packaging

Micro-Bumping



3D Integration

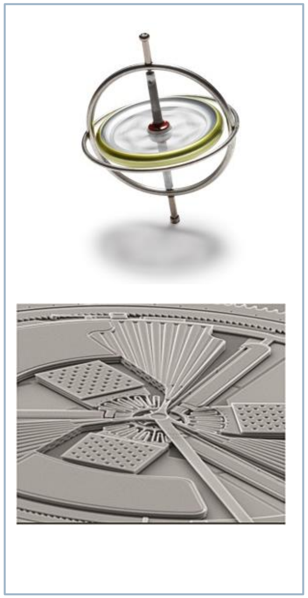
3D (TSV) Stacking



Sensors

MEMS

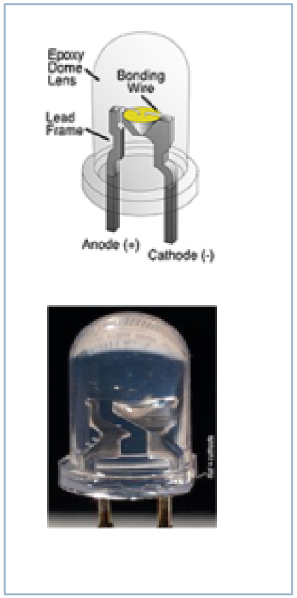
Computing, Automotive...



Lighting

LED

General Lighting, HB and UHB



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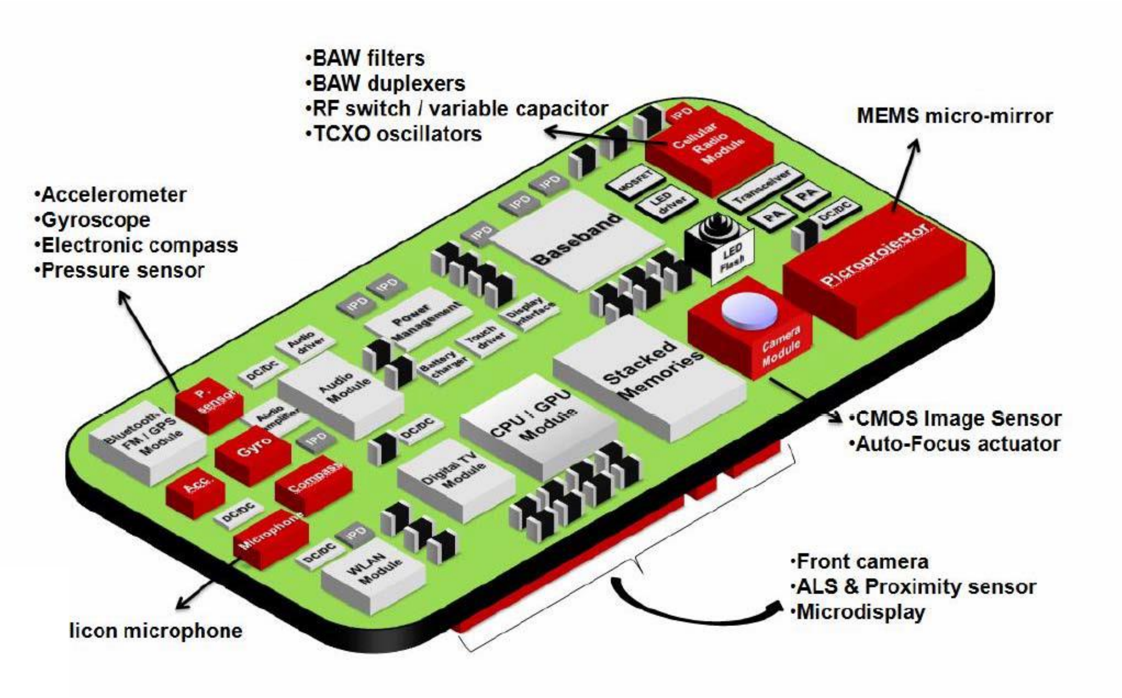
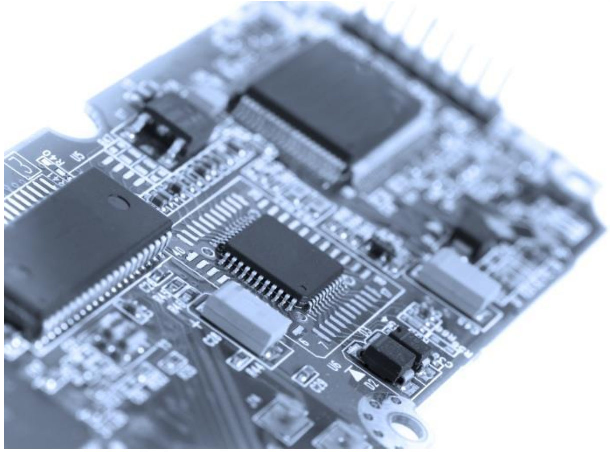
GROWTH DRIVER SMARTPHONES AND TABLETS



Source: Yole Developpement



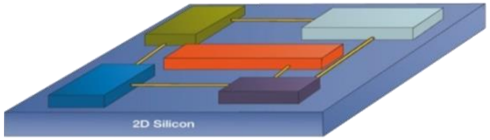
MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle	+ The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media + Mobile devices like smartphones and tablet PCs provide this capability at affordable cost + New device generations offer higher functionality	
E-Mobility	+ Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios + EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices and high performance Ics at the same time	
Energy Efficiency	+ Increased environmental awareness and rising energy cost drive the demand for energy efficient solutions i.e. solid state lighting + Energy efficiency in industrial production + Smart energy management in household applications	

SCALING TECHNOLOGIES FROM 2D TO 3D

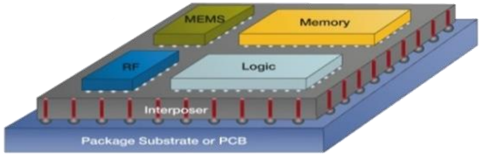
2D Packaging

- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore‘s Law
- New technologies like EUV and multiple pattering allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size



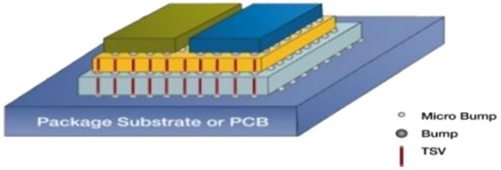
2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore‘s Law



3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore“
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec‘s equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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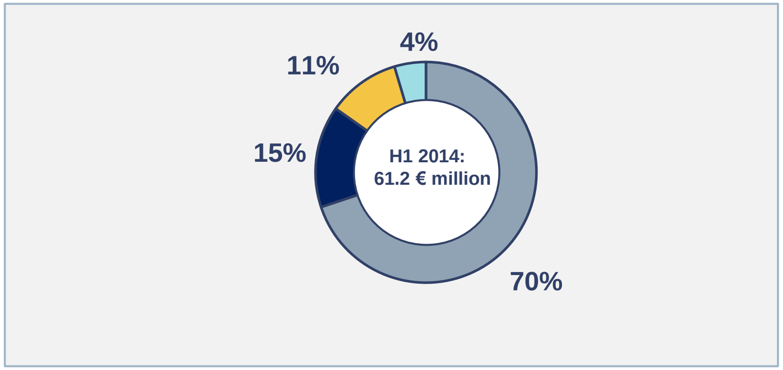
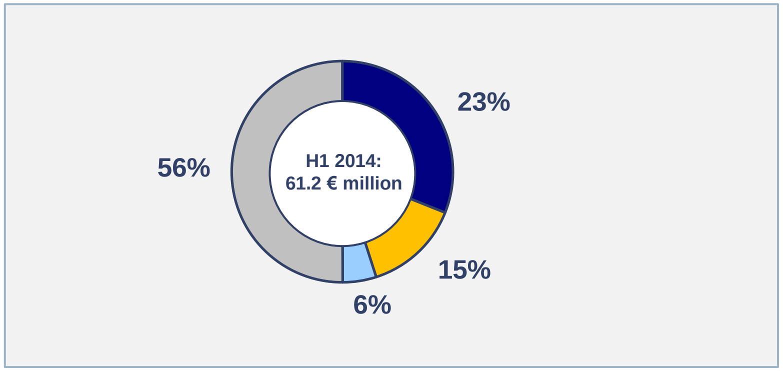
ORDER ENTRY AND SALES BY SEGMENT AND REGION

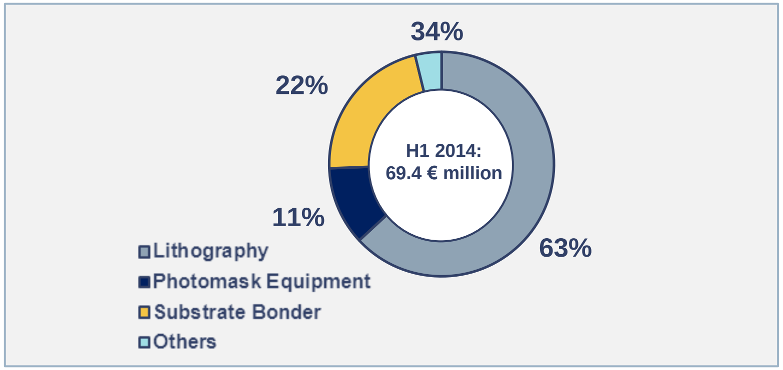
Order Entry by Segment



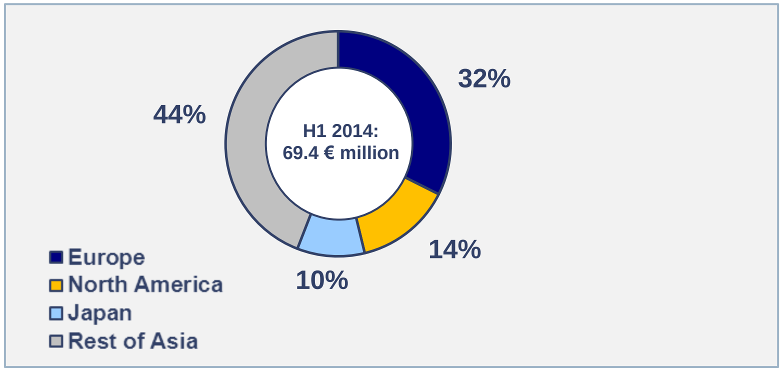
Order Entry by Region



Sales by Segment

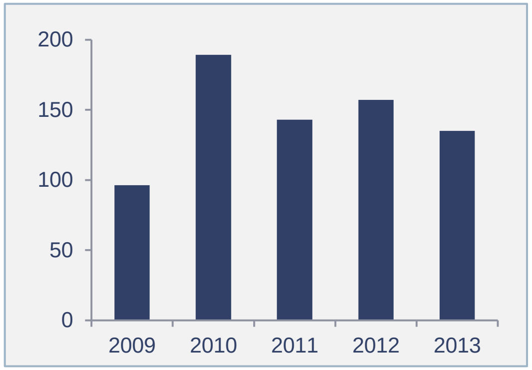


Sales by Region

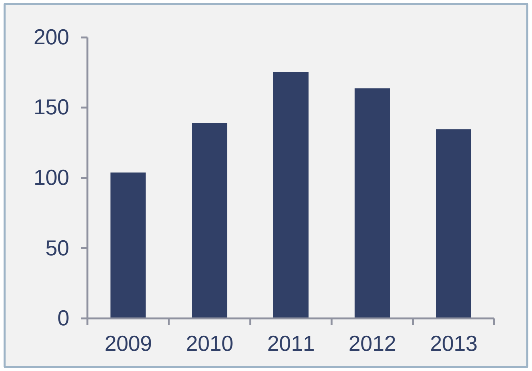


LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

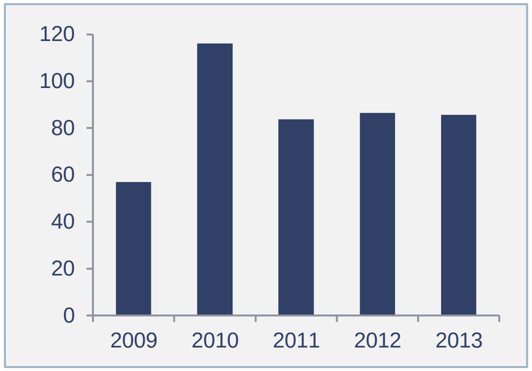
Order Entry in € million



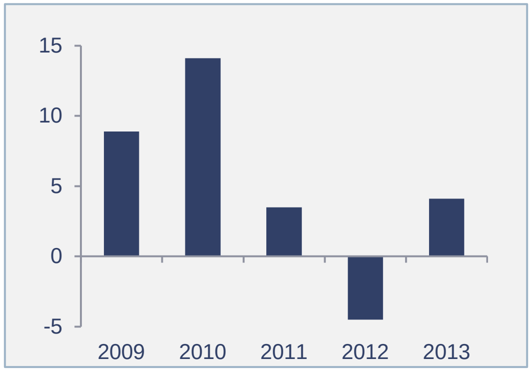
Sales in € million



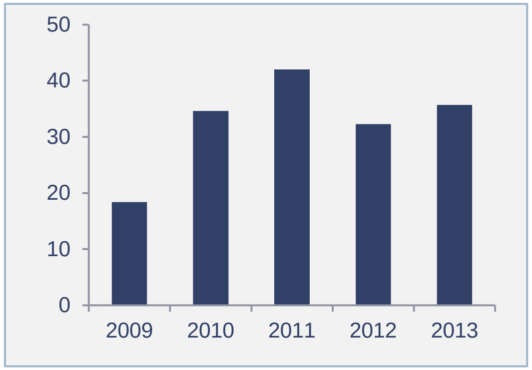
Order backlog in € million



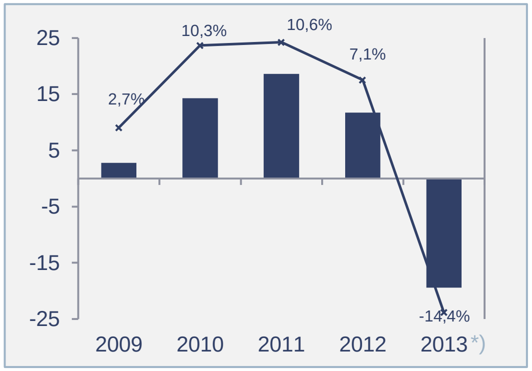
Free Cash Flow in € million



Net cash in € million



EBIT in € million



* Including a -13.2 € milion one-off effect from restructuring of the product line permanant bonding (-0,69 € per share)

KEY FINANCIALS

in € million	Q2 2014	Q2 2013	in %	*H1 2014*	*H1 2013*
Order Intake	**36.2**	**36.7**	**-1.4%**	***61.2***	***71.6***
Order Backlog 6/30	**--**	**--**	**--**	***77.7***	***102.5***
Revenue	**30.4**	**24.9**	**+22.1%**	***69.4***	***55.0***
EBIT	**1.9**	**-11.7**	**--**	***3.4***	***-15.0***
EBIT in % of Sales	*6.3%*	*-47,0%*	--	*4.9%*	*-27.3%*
EBIT (adjusted)	**--**	**-5.7**	**--**	***--***	***-9.0***
EBIT (adjusted) in % of Sales	--	*-22.8%*	--	--	*-16.4%*
Earnings after tax	**0.9**	**-9.1**	**--**	***2.0***	***-11.6***
EPS in €	**0.05**	**-0.48**	**--**	***0.11***	***-0.61***
Free Cash Flow*	**1.8**	**-5.2**	**--**	***-2.4***	***-12.4***
Net Cash**	**--**	**--**	**--**	***33.3***	***19.5***
Employees 6/30	**--**	**--**	**--**	***649***	***680***

* incl. stock of interest-bearing securities
** before consideration of purchased interest-bearing securities

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OUTLOOK PER PRODUCT LINE

Lithography	**Mask Aligner and Coaters /Developers** **Current and expected sales level around 80 – 90 € million per year** **UV Projection Scanners, and Laser Ablation Steppers:** Several customer installations; the products are in an early market introduction phase **Current annual sales at around 10 € million**
Photomask Equipment	**Stable sales level at around € 20 million per year**
Substrate Bonders	**Permanent Bonding** After discontinuation of cluster systems reduced sales level vs. previous years **Temporary Bonding** 3D integration is a significant growth opportunity with volume ramp difficult to predict **Expected sales level of the division: 15 – 20 € million**

OUTLOOK

Improved Guidance	FY 2014: Sales: 135 to 145 € million EBIT: slightly positive
Outlook	Q3 2014: Order Intake: 25 - 35 € million Q4 2014: Order Intake: 30 - 40 € million

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ORGANIZATIONAL STRUCTURE SUSS GROUP

Management Board

Michael Knopp, CFO (Speaker)	Walter Braun, COO

Finance, Tax, Legal, HR, IT, Sales, Service & Marketing, Strategy, Investor Relations

Operations, Quality, Supply Chain Management, R & D, Patents, Environmental Protection, Work Safety, Strategy

Divisions

Lithography	Photomask Equipment	Bonder

Sales & Service

Europe, USA, Japan, China, Taiwan, Singapore, Korea

INVESTOR RELATIONS INFORMATION

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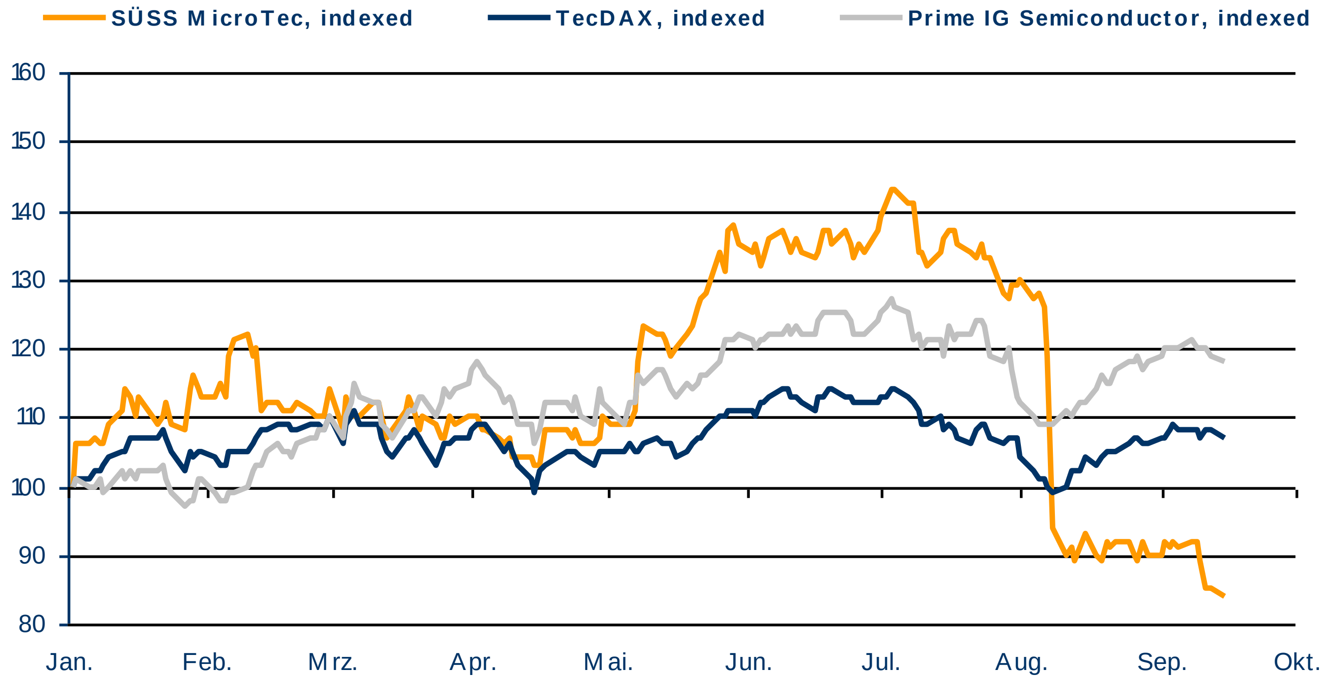
Financial Calendar 2014 / 2015

German Corporate Conference, Berenberg/Goldman Sachs, München	22. Sep.
Neunmonatsbericht 2014	6. Nov.
Eigenkapitalforum 2014, Frankfurt am Main	24. - 26. Nov.

KeplerCheuvreux Investorenkonferenz, Frankfurt	19. Jan.
Geschäftsbericht 2013	30. Mrz.
Quartalsbericht 2014	7. Mai.

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SUSS MicroTec Share at January 2, 2014: 6.38 €)

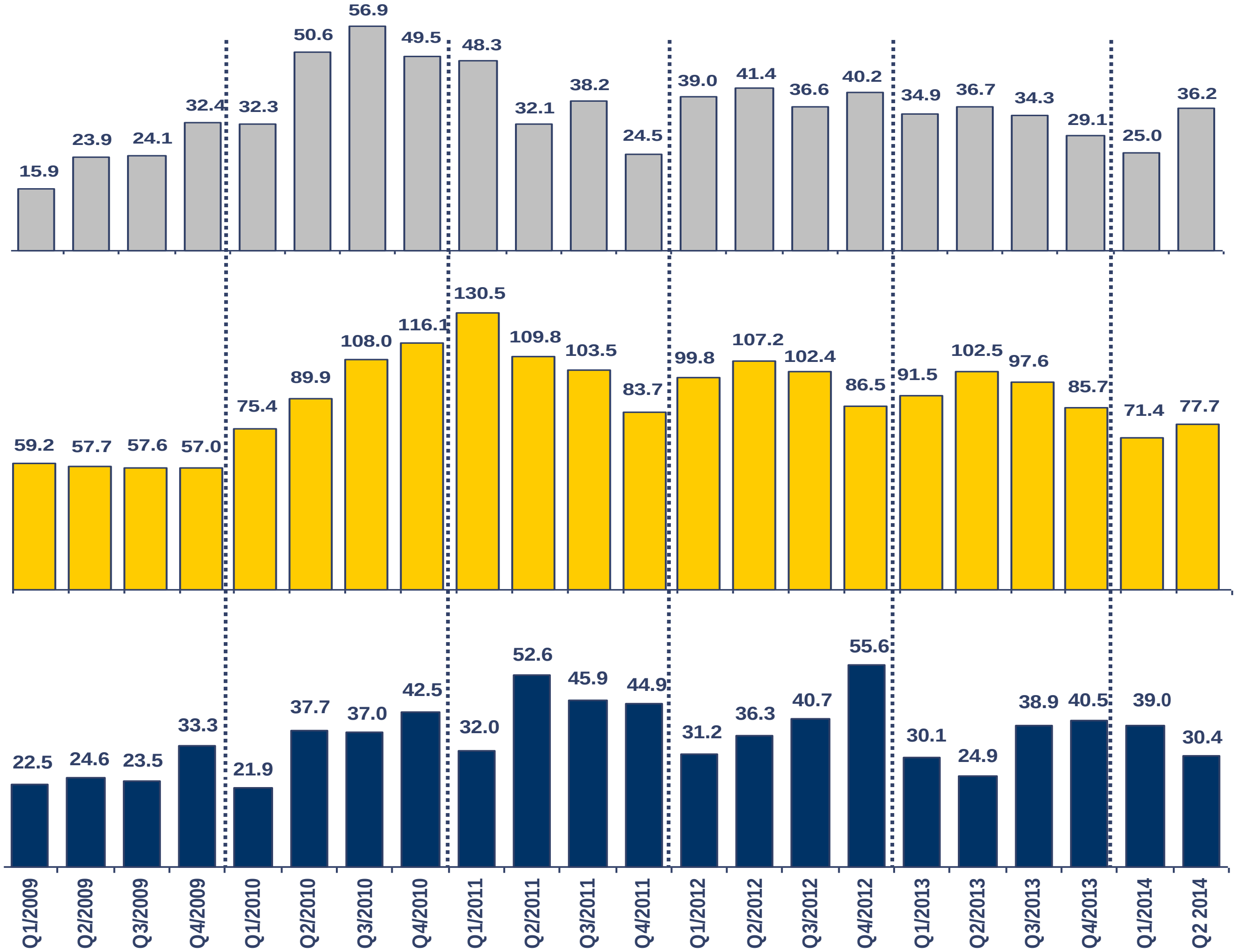


Major Shareholders:

Henderson	5.13%
ING Invest	3.42%
Vanguard	3.20%
Sycomore	3.14%
Schroders	3.10%
Baillie Gifford	3.00%

Average daily trading volume January 2014 – September 2014: ~ 103,000

LONG TERM BUSINESS DEVELOPMENT BY QUARTER

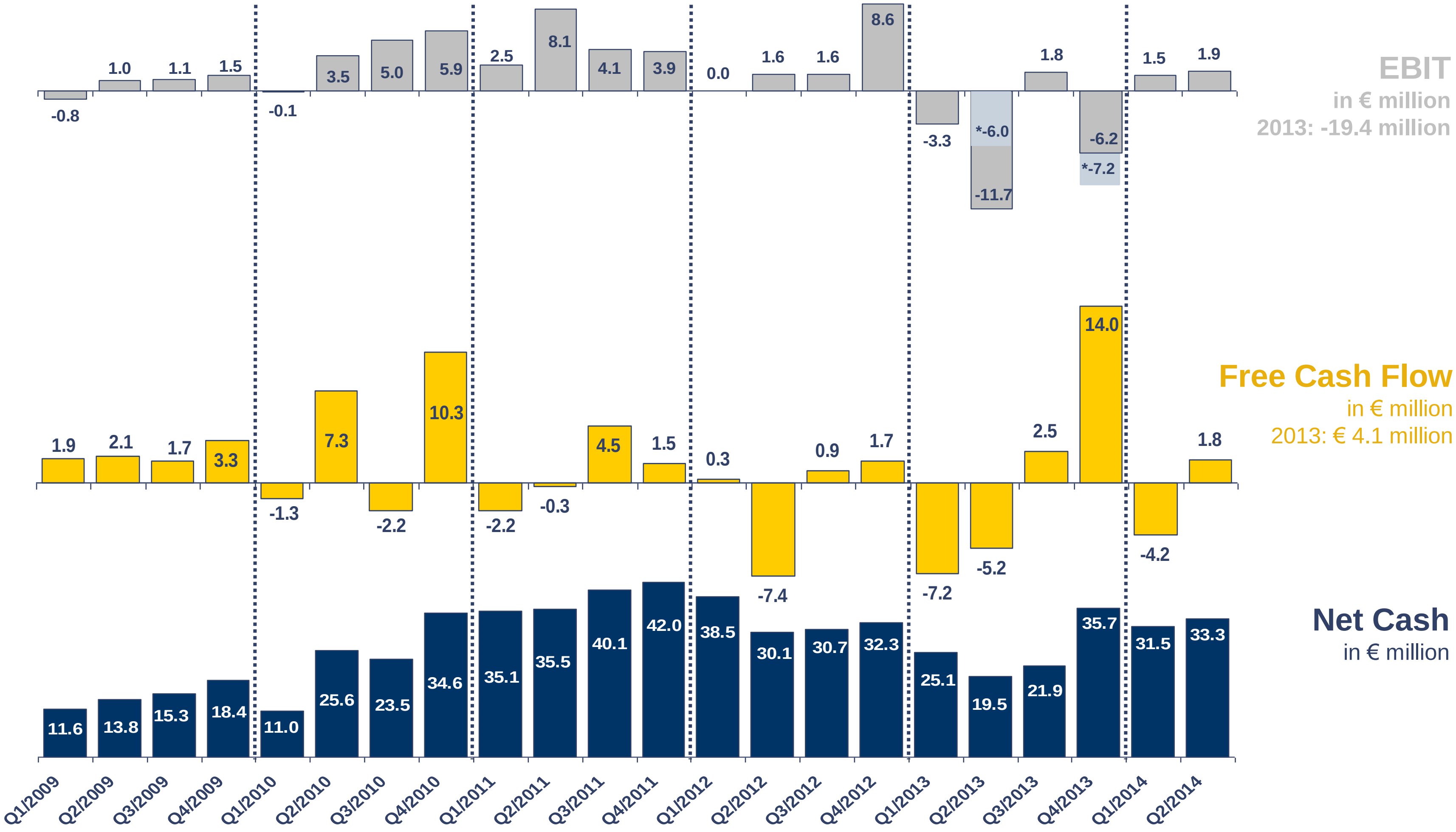


Order Entry
in € million
2013: € 135 million

Order Backlog
in € million

Sales
in € million
2013: € 135 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding